



瑞晶電子股份有限公司
Rexchip Electronics Corp.

Elpida to Set Up R&D Center at Rexchip to Develop 40nm 4F² Process Technology

Houli, Taiwan, January 5, 2010 – Rexchip Electronics is a leading DRAM manufacturer in Taiwan. Its 300mm fabrication facility utilizes the most advanced technology to manufacture high density and high performance DRAM products. Today, January 5th, Rexchip Electronics and Elpida Memory jointly announce the establishment of a technology development center at Rexchip during the first quarter of 2010, cooperating on the development of the next generation 40nm 4F² process technology, beginning with front-end technology, gradually utilizing Rexchip as the Taiwan PC DRAM design center. This decision also allows Taiwan to achieve the goal of possessing independent DRAM process technology.

At the same time, Rexchip Electronics also announces that in 2010 it will migrate to 40nm 6F² process technology, mass producing 2Gb DDR3 products. Currently both parties plan for Rexchip's 80,000 12" monthly wafers to be fully converted to 40nm 6F² process technology by the end of 2010. If the market demand is not as expected, Rexchip will first migrate half of its capacity, with the remainder utilizing 65nm-XS process technology. As a result of Rexchip's 65nm-XS process chip size being equivalent to other DRAM manufacturers' 50nm process, under these conditions, Rexchip is still capable of possessing comparable competitive technology. Furthermore, Elpida's Hiroshima Fab has already, at the end of 2009, completed the pilot run of the 40nm 6F² process, where yields have already exceeded expectations, where Elpida initially plans for half of its 130,000 12" wafers per month to be converted and further conversion dependent on market conditions.

As the 40nm 6F² process technology reduces the chip size, when compared to the current generation of 65nm products, this will effectively reduce relative die costs by 50%. This process is also the most advanced among industry peers, with the smallest die size, producing high performance and low power consumption, mainstream DDR3 products. Rexchip leading Taiwan peers, using this advanced process, following the creation of the R&D center, will with Elpida concurrently upgrade its process technology, maintaining its competitive advantage. Elpida, at the

same time announces, that the process technology also depending on certain conditions be transferred to manufacturing partners Powerchip Semiconductor, Winbond, and Promos. Going forward both parties joint-development costs will be even lower, producing higher efficiency superior products and integrating outstanding production capabilities to create a win-win situation for both parties.

Contact : Sandy Kuo (886-4-25218000 ext. 8091)